IGBT die nomenclature

Device type
G = IGBT chip

Technology
S = Gen 5
4 = Gen 4
Blank = Gen 3

Package type
C = No package (chip only)

Voltage
C = 600V
H = 1200V

Die size
3 = Die size 3
4 = Die size 4
5 = Die size 5

Lead option
A = Lead form down*
B = Lead form up
C = Lead trimmed (clipped)
*Lead attach if package is SMD

Screening level
SCX = TXlevel
SCV = TXVlevel
SCS = Space level

Speed
U = Ultra fast
F = Fast
S = Standard